

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

Rating	Suffix	Symbol	Value	Unit
Peak Repetitive Off-State Voltage ^(Note 1) ($T_J = 25$ to 100°C , Gate Open) T2322, T2323	F	V_{DRM}	50	V
	A		100	
	B		200	
	C		300	
	D		400	
	E		500	
	M		600	
RMS On-State Current ($T_C = 70^\circ\text{C}$) (Full Cycle Sine Wave 50 to 60 Hz)		$I_{\text{T(RMS)}}$	2.5	A
Peak Non-Repetitive Surge Current (One Full Cycle, 60 Hz)		I_{TSM}	25	A
Circuit Fusing ($t \leq 8.3\text{ms}$)		I^2t	2.6	A^2s
Peak-Gate Power ($1\mu\text{s}$)		P_{GM}	10	W
Average Gate Power ($T_C = 60^\circ\text{C}$)		$P_{\text{G(AV)}}$	0.15	W
Peak Gate Current ($1\mu\text{s}$)		I_{GM}	0.5	A
Operating Junction Temperature Range		T_J	-40 to +110	$^\circ\text{C}$
Storage Temperature Range		T_{stg}	-40 to +150	$^\circ\text{C}$
Mounting Torque (6-32 Screw) ^(Note 2)		-	8.0	In. lb.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	3.5	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Ambient	$R_{\theta\text{JA}}$	60	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ and either polarity of MT2 to MT1 voltage, unless otherwise noted)

Characteristics	Symbol	Min	Typ	Max	Unit	
Peak Blocking Current ($V_D = \text{Rated } V_{\text{DRM}}$, Gate Open)	I_{DRM}	$T_J = 25^\circ\text{C}$	-	10	μA	
		$T_J = 100^\circ\text{C}$	-	0.75	mA	
Peak On-State Voltage ^(Note 3) ($I_{\text{TM}} = 10\text{A}$)	V_{TM}	T2323 Series	-	1.7	V	
		T2322 Series	-	1.7	2.2	
Gate Trigger Current (Continuous dc) ($V_D = 12\text{V}$, $R_L = 30\Omega$) All Modes MT2(+), G(+); MT2(-), G(-) MT2(+), G(-); MT2(-), G(+)	I_{GT}	T2322 Series	-	-	10	mA
		T2323 Series	-	-	25	
		T2323 Series	-	-	40	
Gate Trigger Voltage (Continuous dc) ($V_D = 12\text{Vdc}$, $R_L = 30\Omega$, $T_C = 25^\circ\text{C}$) ($V_D = V_{\text{DRM}}$, $R_L = 125\Omega$, $T_C = 100^\circ\text{C}$)	V_{GT}		-	1	V	
			0.15	-	-	

T2322, T2323 SERIES

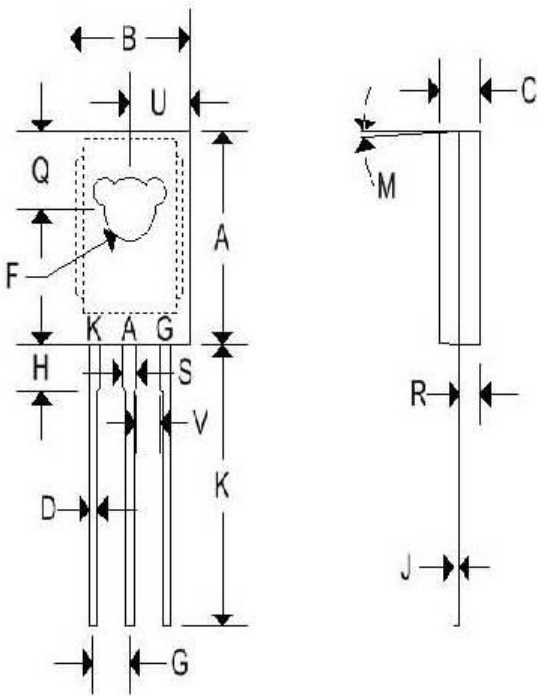
SILICON BIDIRECTIONAL THYRISTORS

Holding Current ($V_D = 12V$, $I_{TM} = 150mA$, Gate Open)	I_H	-	15	30	mA
Gate Controlled Turn-On Time ($V_D = \text{Rated } V_{DRM}$, $I_{TM} = 10A$ pk, $I_G = 60mA$)	t_{gt}	-	1.8	2.5	μs
Critical Rate of Rise of Off-State Voltage ($V_D = \text{Rated } V_{DRM}$, Exponential Waveform, $T_C = 100^\circ C$)	dv/dt	10	100	-	$V/\mu s$
Critical Rate of Rise of Commutation Voltage ($V_D = \text{Rated } V_{DRM}$, $I_{TM} = 3.5 A$ pk, Commutating $di/dt = 1.26 A/ms$, Gate Unenergized, $T_C = 90^\circ C$)	$dv/dt(c)$	1.0	4.0	-	$V/\mu s$

Note 1: V_{DRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.
 Note 2: Torque rating applies with use of torque washer. Mounting Torque in excess of 6 in. lb. does not appreciably lower case-to-sink thermal resistance. Main terminal 2 and heat-sink contact pad are common. For soldering purposes (either terminal connection or device mounting), soldering temperatures shall not exceed $+200^\circ C$, for 10 seconds.
 Note 3: Pulse Test: Pulse Width $\leq 300ms$, Duty Cycle $\leq 2\%$.

MECHANICAL CHARACTERISTICS

Case	TO-126
Marking	Alpha-numeric
Pin out	See below



	TO-126			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.425	0.435	10.80	11.050
B	0.295	0.305	7.490	7.750
C	0.095	0.105	2.410	2.670
D	0.020	0.026	0.510	0.660
F	0.115	0.125	2.920	3.180
G	0.091	0.097	2.310	2.460
H	0.050	0.095	1.270	2.410
J	0.015	0.025	0.380	0.640
K	0.595	0.655	15.110	16.640
M	3° TYP		3° TYP	
Q	0.148	0.158	3.760	4.010
R	0.045	0.055	1.140	1.400
S	0.025	0.035	0.640	0.890
U	0.145	0.155	3.680	3.940
V	0.040	-	1.020	-